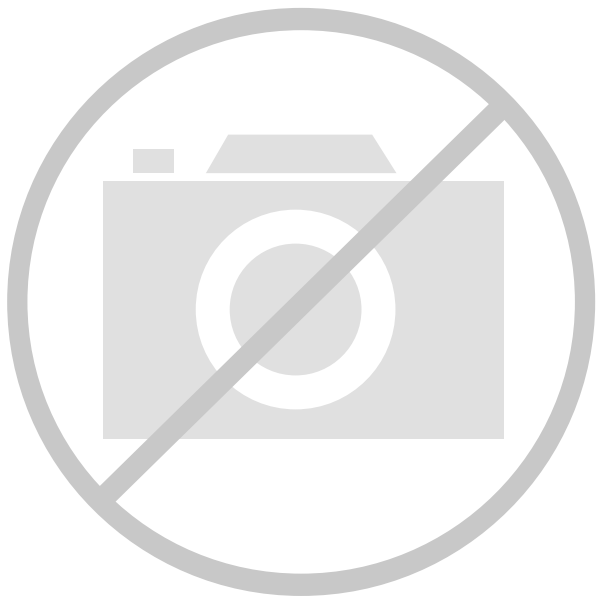




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Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	68000
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	25MHz
Co-Processors/DSP	-
RAM Controllers	-
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	-40°C ~ 85°C (TC)
Security Features	-
Package / Case	132-BCQFP
Supplier Device Package	132-CQFP (24.13x24.13)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts68020vf25

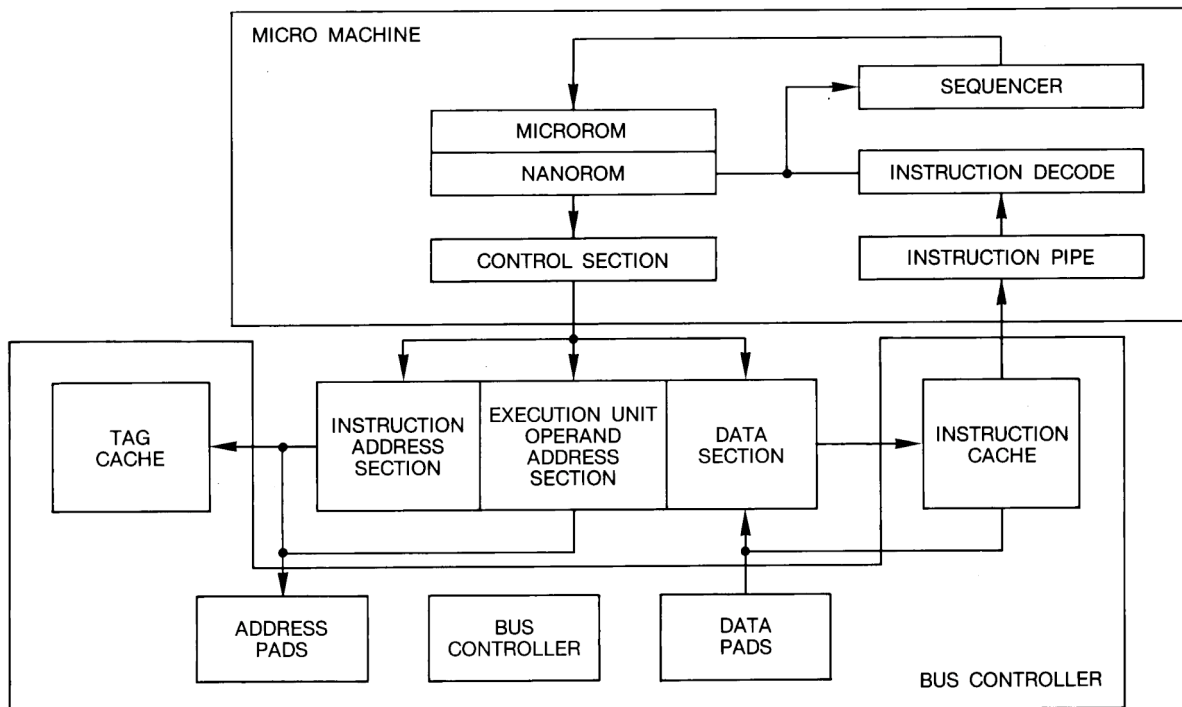
Introduction

The TS68020 is a high-performance 32-bit microprocessor. It is the first microprocessor to have evolved from a 16-bit machine to a full 32-bit machine that provides 32-bit address and data buses as well as 32-bit internal structures. Many techniques were utilized to improve performance and at the same time maintain compatibility with other processors of the TS68000 Family. Among the improvements are new addressing modes which better support high-level language structures, an expanded instruction set which provides 32-bit operations for the limited cases not supported by the TS68000 and several new instructions which support new data types. For special-purpose applications when a general-purpose processor alone is not adequate, a co-processor interface is provided.

The TS68020 is a high-performance microprocessor implemented in HCMOS, low power, small geometry process. This process allows CMOS and HMOS (high density NMOS) gates to be combined on the same device. CMOS structures are used where speed and low power is required, and HMOS structures are used where minimum silicon area is desired. This technology enables the TS68020 to be very fast while consuming less power (less than 1.5 watts) and still have a reasonably small die size. It utilizes about 190,000 transistors, 103,000 of which are actually implemented. The package is a pin-grid array (PGA) with 114 pins, arranged 13 pins on a side with a depopulated center and 132 pins ceramic quad flat pack.

Figure 1 is a block diagram of the TS68020. The processor can be divided into two main sections: the bus controller and the micromachine. This division reflects the autonomy with which the sections operate.

Figure 1. TS68020 Block Diagram



The bus controller consists of the address and data pads and multiplexers required to support dynamic bus sizing, a macro bus controller which schedules the bus cycles on the basis of priority with two state machines (one to control the bus cycles for operated accesses and the other to control the bus cycles for instruction accesses), and the instruction cache with its associated control.

The micromachine consists of an execution unit, nanorom and microrom storage, an instruction decoder, an instruction pipe, and associated control sections. The execution unit consists of an address section, an operand address section, and a data section. Microcode control is provided by a modified two-level store of microrom and nanorom. Programmed logical arrays (PLAs) are used to provide instruction decode and sequencing information. The instruction pipe and other individual control sections provide the secondary decode of instructions and generated the actual control signals that result in the decoding and interpretation of nanorom and microrom information.

Figure 2. PGA Terminal Designation

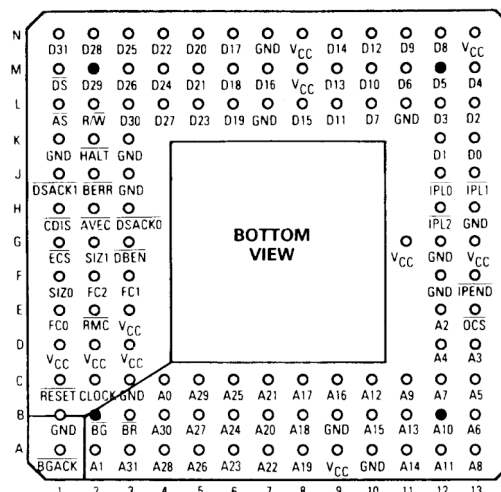


Figure 3. CQFP Terminal Designation

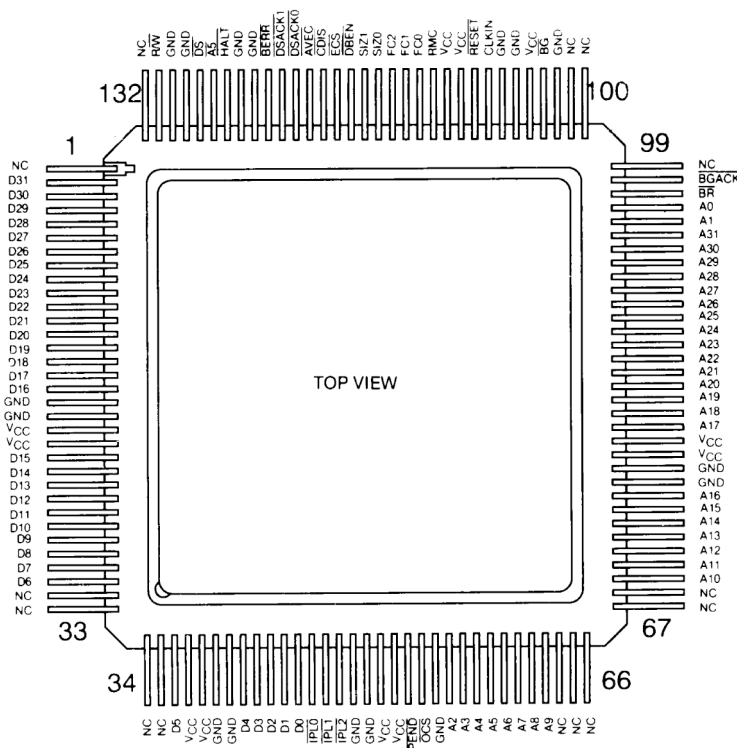
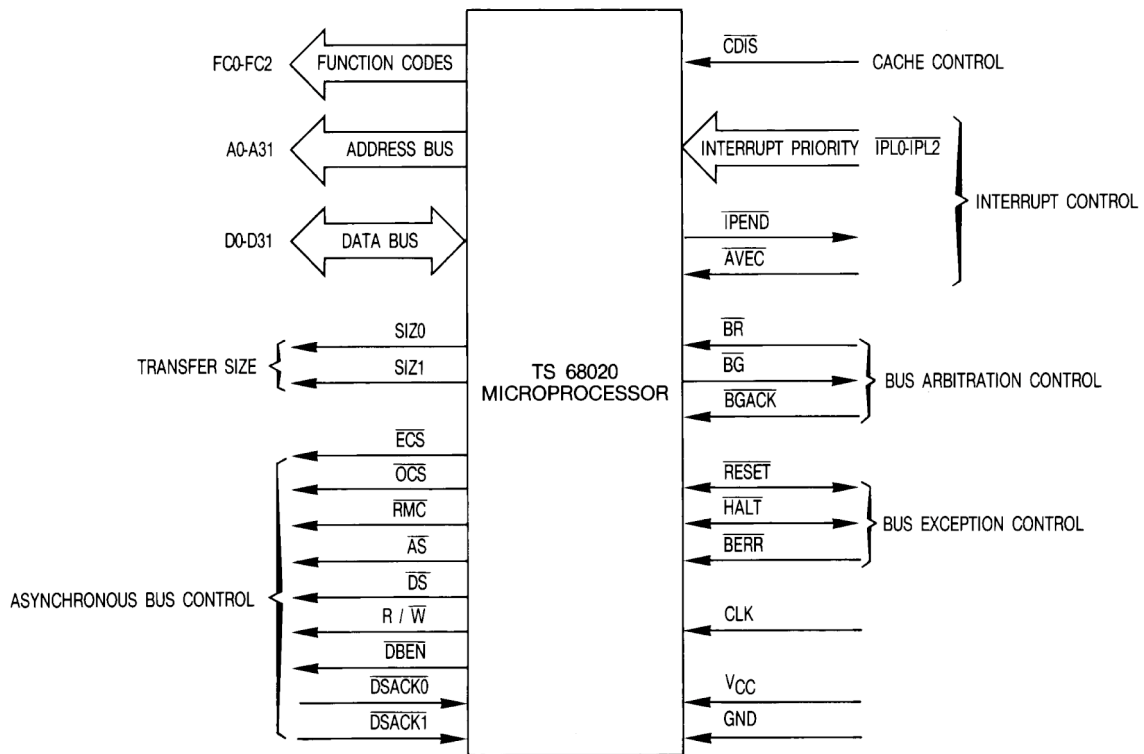


Figure 4. Functional Signal Groups



Signal Description

Figure 4 illustrates the functional signal groups and Table 1 lists the signals and their function.

The V_{CC} and GND pins are separated into four groups to provide individual power supply connections for the address bus buffers, data bus buffers, and all other output buffers and internal logic.

Group	V_{CC}	GND
Address Bus	A9, D3	A10, B9,C3, F12
Data Bus	M8, N8, N13	L7, L11, N7, K3
Logic	D1, D2, E3, G11, G13	G12, H13, J3, K1
Clock	—	B1

Table 1. Signal Index

Signal Name	Mnemonic	Function
Address Bus	A0-A31	32-bit Address Bus Used to address any of 4, 294, 967, 296 bytes.
Data Bus	D0-D31	32-bit Data Bus Used to Transfer 8, 16, 24 or 32 bits of Data Per Bus Cycle.
Function Codes	FC0-FC2	3-bit Function Case Used to Identify the Address Space of Each Bus Cycle.
Size	SIZ0/SIZ1	Indicates the Number of Bytes Remaining to be Transferred for this Cycle. These Signals, Together with A0 And A1, Define the Active Sections of the Data Bus.
Read-Modify-Write Cycle	$\overline{RMC}$	Provides an Indicator that the Current Bus Cycle is Part of an Indivisible read-modify-write Operation.
External Cycle Start	$\overline{ECS}$	Provides an Indication that a Bus Cycle is Beginning.
Operand Cycle Start	$\overline{OCS}$	Identical Operation to that of ECS Except that OCS Is Asserted Only During the First Bus Cycle of an Operand Transfer.
Address Strobe	$\overline{AS}$	Indicates that a Valid Address is on The Bus.
Data Strobe	$\overline{DS}$	Indicates that Valid Data is to be Placed on the Data Bus by an External Device or has been Laced on the Data Bus by the TS68020.
Read/Write	$R/\overline{W}$	Defines the Bus Transfer as an MPU Read or Write.
Data Buffer Enable	$\overline{DBEN}$	Provides an Enable Signal for External Data Buffers.
Data Transfer and Size Acknowledge	$\overline{DSACK0}/\overline{DSACK1}$	Bus Response Signals that Indicate the Requested Data Transfer Operation is Completed. In Addition, these Two Lines Indicate the Size of the External Bus Port on a Cycle-by-cycle Basis.
Cache Disable	$\overline{CDIS}$	Dynamically Disables the On-chip Cache to Assist Emulator Support.
Interrupt Priority Level	$\overline{IPL0-IPL2}$	Provides an Encoded Interrupt Level to the Processor.
Autovector	$\overline{AVEC}$	Requests an Autovector During an Interrupt Acknowledge Cycle.
Interrupt Pending	$\overline{IPEND}$	Indicates that an Interrupt is Pending.
Bus Request	$\overline{BR}$	Indicates that an External Device Requires Bus Mastership.
Bus Grant	$\overline{BG}$	Indicates that an External Device may Assume Bus Mastership.
Bus Grant Acknowledge	$\overline{BGACK}$	Indicates that an External Device has Assumed Bus Mastership.
Reset	$\overline{RESET}$	System Reset.
Halt	$\overline{HALT}$	Indicates that the Processor Should Suspend Bus Activity.
Bus Error	$\overline{BERR}$	Indicates an Invalid or Illegal Bus Operation is Being Attempted.
Clock	CLK	Clock Input to the Processor.
Power Supply	V _{CC}	+5-volt ± 10% Power Supply.
Ground	GND	Ground Connection.

Detailed Specifications

Scope

This drawing describes the specific requirements for the microprocessor 68020, 16.67 MHz, 20 MHz and 25 MHz, in compliance with the MIL-STD-883 class B.

Applicable Documents

MIL-STD-883

- MIL-STD-883: Test Methods and Procedures for Electronics
- MIL-PRF-38535 appendix A: General Specifications for Microcircuits
- Desc Drawing 5962 - 860320xxx

Requirements

General

The microcircuits are in accordance with the applicable document and as specified herein.

Design and Construction

Terminal Connections

Depending on the package, the terminal connections shall be as shown in Figure 2 and Figure 3.

Lead Material and Finish

Lead material and finish shall be any option of MIL-STD-1835.

Package

The macrocircuits are packages in hermetically sealed ceramic packages which are conform to case outlines of MIL-STD-1835 (when defined):

- 114-pin SQ.PGA UP PAE Outline
- 132-pin Ceramic Quad Flat Pack CQFP

The precise case outlines are described on Figure 23 and Figure 24.

For dynamic characteristics (Table 6), test methods refer to IEC 748-2 method, where existing.

Indication of “min.” or “max.” in the column “test temperature” means minimum or maximum operating temperature.

Table 5. Static Characteristics. $V_{CC} = 5.0V_{DC} \pm 10\%$; $GND = 0V_{DC}$; $T_c = -55/+125^\circ C$ or $-40/+85^\circ C$ (Figure 4 to Figure 8)

Symbol	Parameter	Condition	Min	Max	Units
I_{CC}	Maximum Supply Current	$V_{CC} = 5.5V$ $T_{case} = -55^\circ C$ to $+25^\circ C$		333	mA
I_{CC}	Maximum Supply Current	$V_{CC} = 5.5V$ $T_{case} = 125^\circ C$		207	mA
V_{IH}	High Level Input Voltage	$V_O = 0.5V$ or 2.5 $V_{CC} = 4.5V$ to $5.5V$	2.0	V_{CC}	V
V_{IL}	Low Level Input Voltage	$V_O = 0.5V$ or $2.4V$ $V_{CC} = 4.5V$ to $5.5V$	-0.5	0.8	V
V_{OH}	High Level Output Voltage All Outputs	$I_{OH} = 400 \mu A$	2.4		V
V_{OL}	Low Level Output Voltage Outputs A0-A31, FC0-FC2, D0-D31, SIZ0-SIZ1, $\overline{BG}$	$I_{OL} = 3.2 \text{ mA}$ Load Circuit as Figure 8 $R = 1.22 \text{ k}\Omega$		0.5	V
V_{OL}	Low Level Output Voltage Outputs $\overline{AS}$, $\overline{DS}$, $\overline{RMC}$, $\overline{R/W}$, $\overline{DBEN}$, $\overline{IPEND}$	$I_{OL} = 5.3 \text{ mA}$ Load Circuit as Figure 8 $R = 740\Omega$		0.5	V
V_{OL}	Low Level Output Voltage Outputs $\overline{ECS}$, $\overline{OCS}$	$I_{OL} = 2.0 \text{ mA}$ Load Circuit as Figure 8 $R = 2 \text{ k}\Omega$		0.5	V
V_{OL}	Low Level Output Voltage Outputs $\overline{HALT}$, $\overline{RESET}$	$I_{OL} = 10.7 \text{ mA}$ Load Circuit as Figure 6 and Figure 7		0.5	V
$ I_{IN} $	Input Leakage Current (High and Low State)	$-0.5V \leq V_{IN} \leq V_{CC} \text{ (Max)}$		2.5	μA
$ I_{OHZ} $	High level leakage current at three-state outputs Outputs A0-A31, $\overline{AS}$, $\overline{DBEN}$, $\overline{DS}$, D0-D31, $\overline{R/W}$, FC0-FC2, $\overline{RMC}$, SIZ0-SIZ1	$V_{OH} = 2.4V$		2.5	μA
$ I_{OLZ} $	Low Level Leakage Current at Three-state Outputs Outputs A0-A31, $\overline{AS}$, $\overline{DBEN}$, $\overline{DS}$, D0-D31 $\overline{R/W}$, FC0-FC2, $\overline{RMC}$, SIZ0-SIZ1	$V_{OL} = 0.5V$		2.5	μA
I_{OS}	Output Short-circuit Current (Any Output)	$V_{CC} = 5.5V$ $V_O = 0V$ (Pulsed. Duration 1 ms Duty Cycle 10:1)		200	mA

Table 6. Dynamic Electrical Characteristics (Continued)

Symbol	Parameter	Interval Number	68020-16		68020-20		68020-25		Unit	Notes
			Min	Max	Min	Max	Min	Max		
t _{DVSA}	Data Out Valid to $\overline{DS}$ Asserted (Write) 26	26	15		10		5		ns	(6)
t _{DICL}	Data in Valid to Clock Low (Data Setup)	27	5		5		5		ns	
t _{BELCL}	Late $\overline{BERR}/\overline{HALT}$ Asserted to Clock Low Setup Time	27A	20		15		10		ns	
t _{SNDN}	$\overline{AS}$, $\overline{DS}$ Negated to $\overline{DSACKx}/\overline{BERR}/\overline{HALT}/\overline{AVEC}$ Negated	28	0	80	0	65	0	50	ns	
t _{SNDI}	$\overline{DS}$ Negated to Data On Invalid (Data in Hold Time)	29	0		0		0		ns	(6)
t _{SNDIZ}	$\overline{DS}$ Negated to Data in High Impedance	29A		60		50		40	ns	
t _{DADI}	$\overline{DSACKx}$ Asserted to Data In Valid	31		50		43		32		(2)(11)
t _{DADV}	$\overline{DSACK}$ Asserted to $\overline{DSACKx}$ Valid ($\overline{DSACK}$ Asserted Skew)	31A		15		10		10	ns	(3)(11)
t _{HRrf}	$\overline{RESET}$ Input Transition Time	32		1.5		1.5		1.5	Clks	
t _{CLBA}	Clock Low to $\overline{BG}$ Asserted	33	0	30	0	25	0	20	ns	
t _{CLBN}	Clock Low to $\overline{BG}$ Negated	34	0	30	0	25	0	20	ns	
t _{BRAGA}	$\overline{BR}$ Asserted to $\overline{BG}$ Asserted (RMC Not Asserted)	35	1.5	3.5	1.5	3.5	1.5	3.5	Clks	(11)
t _{GAGN}	$\overline{BGACK}$ Asserted to $\overline{BG}$ Negated	37	1.5	3.5	1.5	3.5	1.5	3.5	Clks	(11)
t _{GABRN}	$\overline{BGACK}$ Asserted to $\overline{BR}$ Negated	37A	0	1.5	0	1.5	0	1.5	Clks	(11)
t _{GN}	$\overline{BG}$ Width Negated	39	90		75		60		ns	(11)
t _{GA}	$\overline{BG}$ Width Asserted	39A	90		75		60		ns	
t _{CHDAR}	Clock High to $\overline{DBEN}$ Asserted (Read)	40	0	30	0	25	0	20	ns	
t _{CLDNR}	Clock Low to $\overline{DBEN}$ Negated (Read)	41	0	30	0	25	0	20	ns	
t _{CLDAW}	Clock Low to $\overline{DBEN}$ Negated (Read)	42	0	30	0	25	0	20	ns	
t _{CHDNW}	Clock High to $\overline{DBEN}$ Asserted (Read)	43	0	30	0	25	0	20	ns	
t _{RADA}	R/W Low to $\overline{DBEN}$ Asserted (Write)	44	15		10		10		ns	(6)
t _{DA}	$\overline{DBEN}$ Width Asserted READ WRITE	45							ns	(5)
			60		50		40		ns	(5)
			120		100		80			
t _{RWA}	R/ $\overline{W}$ Width Asserted (Write or Read)	46	150		125		100		ns	
t _{AIST}	Asynchronous Input Setup Time	47A	5		5		5		ns	(11)
t _{AIHT}	Asynchronous Input Hold Time	47B	15		15		10		ns	(11)
t _{DABA}	$\overline{DSACKx}$ Asserted to $\overline{BERR}/\overline{HALT}$ Asserted	48		30		20		18	ns	(4)(11)
t _{DOCH}	Data Out Hold from Clock High	53	0		0		0		ns	
t _{BNHN}	$\overline{BERR}$ Negated to $\overline{HALT}$ Negated (Rerun)		0		0		0		ns	

Test Conditions Specific to the Device

Loading Network

The applicable loading network shall be defined in column “Test conditions” of Table 6, referring to the loading network number as shown in Figure 6, Figure 7, Figure 8 below.

Figure 6. RESET Test Loads

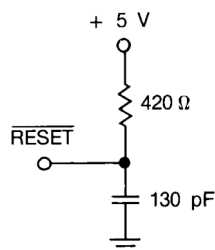


Figure 7. HALT Test Load

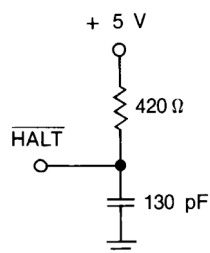


Figure 8. Test Load

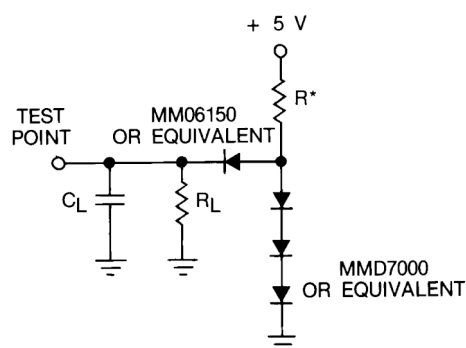
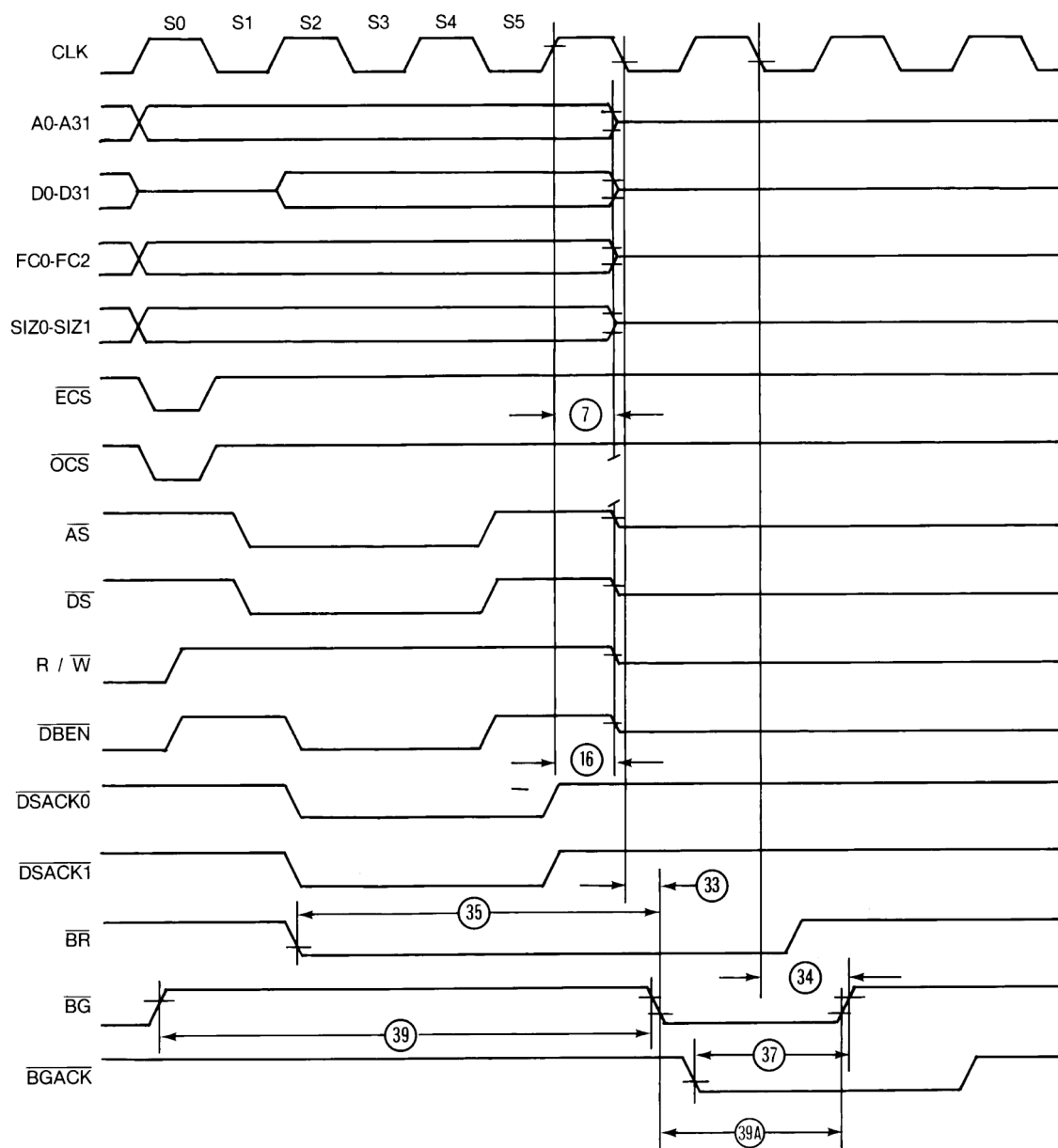


Table 7. Load Network

Load NBR	Figure	R	R_L	C_L	Output Application
1	7	2 k	6.0 k	50 pF	$\overline{OCS}$, $\overline{ECS}$
2	7	1.22 k	6.0 k	130 pF	A0-A31, D0-D31, $\overline{BG}$, FC0-FC2, SIZ0-SIZ1
3	7	0.74 k	6.0 k	130 pF	$\overline{AS}$, $\overline{DS}$, $R/\overline{W}$, $\overline{RMC}$, $\overline{DBEN}$, $\overline{IPEND}$

Note: 1. Equivalent loading may be simulated by the tester.

Figure 11. Bus Arbitration Timing Diagram



Note: Timing measurements are referenced to and from a low voltage of 0.8V and a high voltage of 2.0V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between 0.8V and 2.0V.

Input and Output Signals for Dynamic Measurements

AC Electrical Specifications Definitions

The AC specifications presented consist of output delays, input setup and hold times, and signal skew times. All signals are specified relative to an appropriate edge of the TS68020 clock input and, possibly, relative to one or more other signals.

The measurement of the AC specifications is defined by the waveforms in Figure 12. In order to test the parameters guaranteed by Atmel, inputs must be driven to the voltage levels specified in Figure 12. Outputs of the TS68020 are specified with minimum and/or maximum limits, as appropriate, and are measured as shown. Inputs to the TS68020 are specified with minimum and, as appropriate, maximum setup and hold times, and are measurement as shown. Finally, the measurements for signal-to-signal specification are also shown.

Note that the testing levels used to verify conformance of the TS68020 to the AC specifications does not affect the guaranteed DC operation of the device as specified in the DC electrical characteristics.

Additional Information

Additional information shall not be for any inspection purposes.

Power Consideration

See Table 4.

Capacitance (Not for Inspection Purposes)

Symbol	Parameter	Test Conditions	Min	Unit
C_{in}	Input Capacitance	$V_{in} = 0V$ $T_{amb} = 25^{\circ}C$ $f = 1\text{ MHz}$	20	pF

Capacitance Derating Curves

Figure 13 to Figure 18 inclusive show the typical derating conditions which apply. The capacitance includes any stray capacitance. The graphs may not be linear outside the range shown.

Figure 13. Address Capacitance Derating Curve

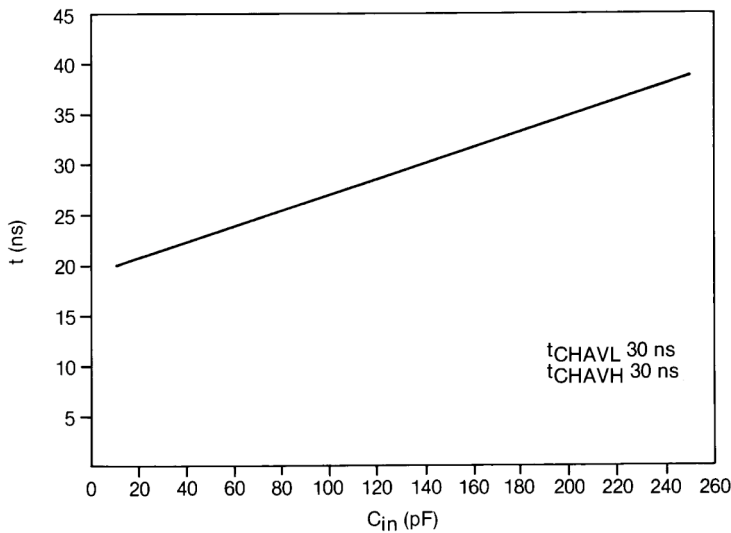
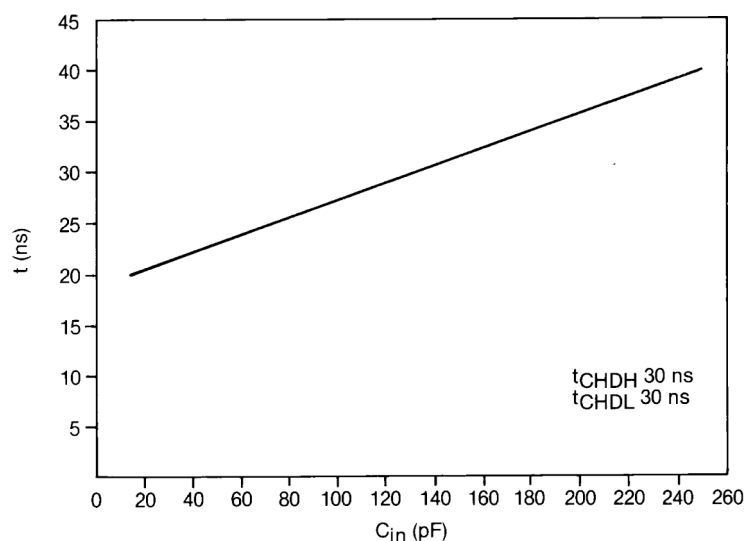


Figure 18. Data Capacitance Derating Curve

Functional Description

Description of Registers

As shown in the programming models (Figure 19 and Figure 20) the TS68020 has sixteen 32-bit general-purpose registers, a 32-bit program counter, two 32-bit supervisor stack pointers, a 16-bit status register, a 32-bit vector base register, two 3-bit alternate function code registers, and two 32-bit cache handling (address and control) registers. Registers D0-D7 are used as data registers for bit and bit field (1- to 32-bit), byte (8-bit), long word (32-bit), and quad word (64-bit) operations. Registers A0-A6 and the user, interrupt, and master stack pointers are address registers that may be used as software stack pointers or base address registers. In addition, the address registers may be used for word and long word operations. All of the 16 (D0-D7, A0-A7) registers may be used as index registers.

The status register (Figure 21) contains the interrupt priority mask (three bits) as well as the condition codes: extend (X), negated (N), zero (Z), overflow (V), and carry (C). Additional control bits indicate that the processor is in the trace mode (T1 or T0), supervisor/user state (S), and master/interrupt state (M).

All microprocessors of the TS68000 Family support instruction tracing (via the T0 status bit in the TS68020) where each instruction executed is followed by a trap to a user-defined trace routine. The TS68020 adds the capability to trace only the change of flow instructions (branch, jump, subroutine call and return, etc.) using the T1 status bit. These features are important for software program development and debug.

The vector base register is used to determine the runtime location of the exception vector table in memory, hence it supports multiple vector tables so each process or task can properly manage exceptions independent of each other.

The TS68000 Family processors distinguish address spaces as supervisor / used and program/data. These four combinations are specified by the function code pins (FC0/FC1/FC2) during bus cycles, indicating the particular address space. Using the function codes, the memory sub-system can distinguish between authorized access (supervisor mode is privileged access) and unauthorized access (user mode may not have access to supervisor program or data areas). To support the full privileges of the supervisor, the alternate function code registers allow the supervisor to specify an access to user program or data areas by preloading the SFC/DFC registers appropriately.

The cache registers (control — CACR, address — CAAR) allow software manipulation of the on-chip instruction cache. Control and status accesses to the instruction cache are provided by the cache control register (CACR), while the cache address register (CAAR) holds the address for those cache control functions that require an address.

Figure 19. User Programming Model

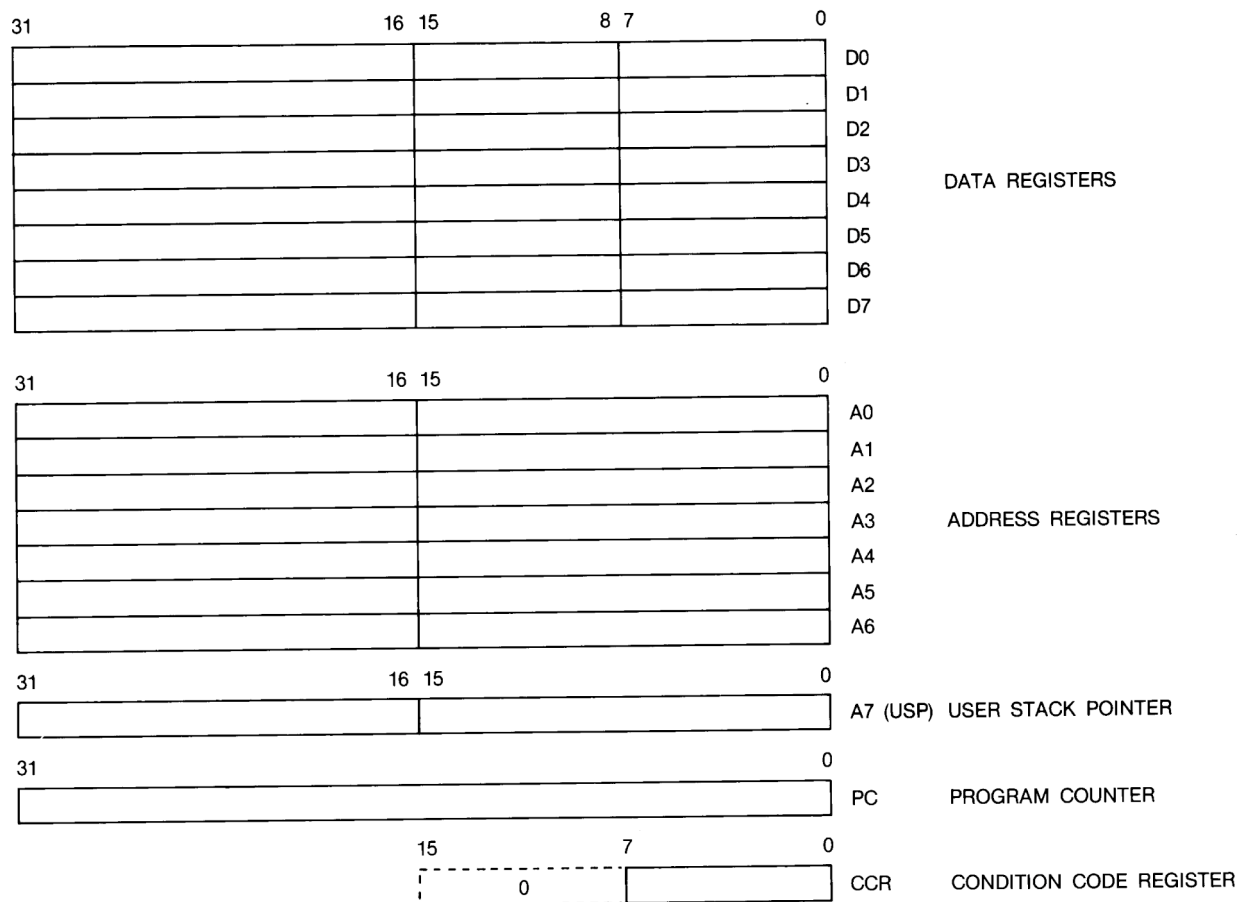
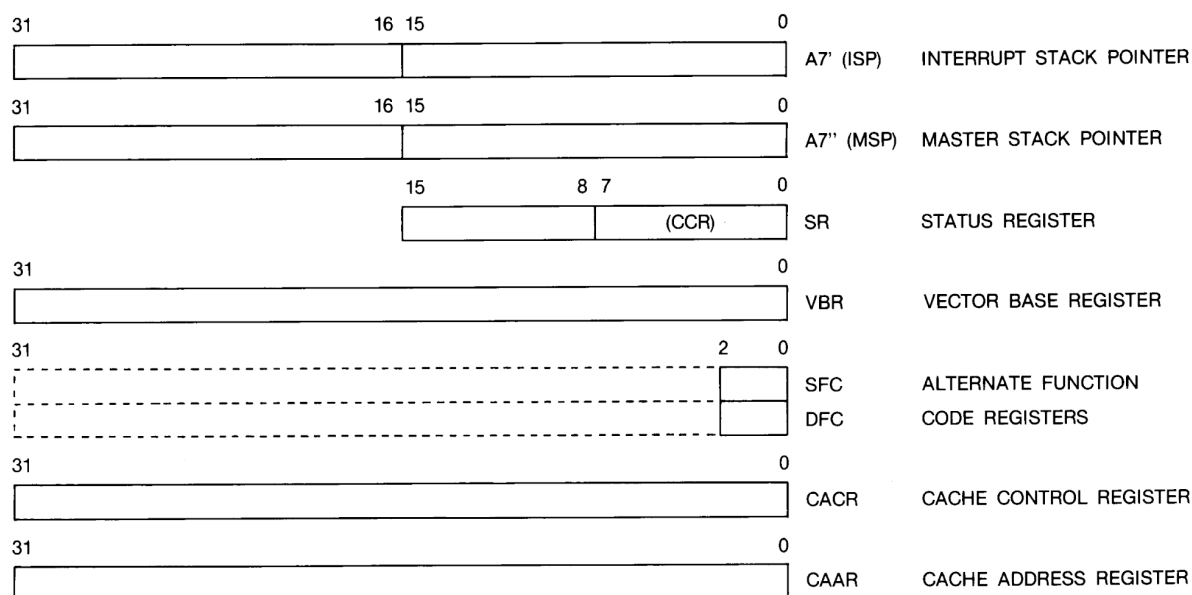
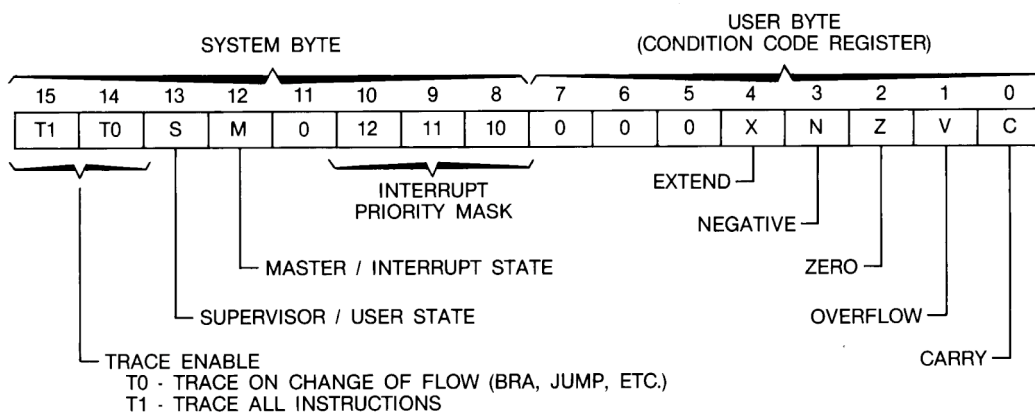


Figure 20. Supervisor Programming Model Supplement

Figure 21. Status Register


Data Types and Addressing Modes

Seven basic types are supported. These data types are:

- Bits
- Bits Flieds (String of consecutive bits, 1-32 bits long)
- BCD Digits (Packed: 2 digits/byte, Unpacked: 1 digit/byte)
- Byte Integers (8-bit)
- Word Integers (16-bit)
- Long Word Integers (32-bit)
- Quad Word Integers (64-bit)

In addition, operations on other data types, such as memory addresses, status word data, etc..., are provided in the instruction set. The co-processor mechanism allows direct support of floating-point data type with the TS68881 and TS68882 floating-point co-processors, as well as specialized user-defined data types and functions.

Table 8. TS68020 Addressing Modes (Continued)

Addressing Modes	Syntax
Absolute	
Absolute Short	xxx.W
Absolute Long	xxx.L
Immediate	=data

- Notes:
1. Dn = Data Register, D0-D7.
 2. An = Address Register, A0-A7.
 3. d₈, d₁₆ = A two's-complement, or sign—extended displacement; added as part of the effective calculation; size is 8 (d₈) or 16 (d₁₆) bits; when omitted assemblers use a value of zero.
 4. Xn = Address or data register used as an index register; form is Xn, SIZE*SCALE, where SIZE is W or L (indicates index register size) and SCALE is 1, 2, 4, or 8 (index register is multiplied by SCALE); use of SIZE and/or SCALE is optional.
 5. bd = A two-complement base displacement; when present, size can be 16- or 32-bit.
 6. od = Outer displacement, added as part of effective address calculation after any memory indirection; use is optional with a size of 16- or 32-bit.
 7. PC = Program Counter.
 8. (data) = Immediate value of 8, 16 or 32 bits.
 9. () = Effective Address.
 10. [] = Use as indirect address to long word address.

Table 9. Instruction Set (Continued)

Mnemonic	Description
OR	Logical Inclusive OR
ORI	Logical Inclusive OR Immediate
PACK	Pack BCD
PEA	Push Effective Address
RESET	Reset External Devices
ROL, ROR	Rotate Left and Right
ROXL, ROXR	Rotate with Extend Left and Right
RTD	Return and Deallocate
RTE	Return and Exception
RTM	Return from Module
RTR	Return and Restore Codes
RTS	Return from Subroutine
SBCD	Subtract Decimal with Extend
Scc	Set Conditionally
STOP	Stop
SUB	Subtract
SUBA	Subtract Address
SUBI	Subtract Immediate
SUBQ	Subtract Quick
SUBX	Subtract with Extend
SWAP	Swap Register Words
TAS	Test Operand and Set
TRAP	Trap
TRAPcc	Trap Conditionally
TRAPV	Trap on Overflow
TST	Test Operand
UNLK	Unlink
UNPK	Unpack BCD
Co-processor Instructions	
cpBCC	Branch Conditionally
cpDBcc	Test Co-processor Condition, Decrement and Branch
cpGEN	Co-processor General Instruction
cpRESTORE	Restore Internal State of Co-processor
cpSAVE	Save Internal State of Co-processor
cpScc	Set Conditionally
cpTRAPcc	Trap Conditionally

Bit Field Operation

The TS68020 supports variable length bit field operations up to 32-bit. A bit field may start in any bit position and span any address boundary for the full length of the bit field, up to the 32-bit maximum. The bit field insert (BFINS) inserts a value into a field. Bit field extract unsigned (BFEXTU) and bit field extract signed (BFEXTS) extract an unsigned or signed value from the field. BFFFO finds the first bit in a bit field that is set. To complement the TS68000 bit manipulation instruction, there are bit field change, clear, set and test instructions (BFCHG, BFCLR, BFSET, BFTST). Using the on-chip barrel shifter, the bit and bit field instructions are very fast and particularly useful in applications using packed bits and bit fields, such as graphics and communications.

Binary Coded Decimal (BCD) Support

The TS68000 Family supports BCD operations including add, subtract, and negation. The TS68020 adds the PACK and UNPACK operations for BCD conversions to and from binary form as well as other conversions, e.g., ASCII and EBCDIC. The PACK instruction reduces two bytes of data into a single byte while UNPACK reverses the operation.

Bounds Checking

Previous 68000 Family members offer variable bounds checking only on the upper limit of the bound. The underlying assumption is that the lower bound is zero. This is expanded on the TS68020 by providing two new instructions, CHK2 and CMP2. These instructions allow checking and comparing of both the upper and lower bounds. These instructions may be either signed or unsigned. The CMP2 instructions sets the condition codes upon completion while the CHK2 instruction, in addition to setting the condition codes, will take a system trap if either boundary condition is exceeded.

System Traps

Three additions have been made to the system trap capabilities of the TS68020. The current TRAPV (trap on overflow) instruction has been expanded to a TRAPcc format where any condition code is allowed to be the trapping condition. And, the TRAPcc instruction is expanded to optionally provide one or two additional words following the trap instruction so user-specified information may be presented to the trap handler. These additional words can be used when needed to provide simple error codes or debug information for interactive runtime debugging or post-mortem program dumps. Compilers may provide direction to run-time execution routines towards handling of specific conditions.

The breakpoint instruction, BKPT, is used to support the program breakpoint function for debug monitors and real-time in-circuit or hardware emulators, and the operation will be dependent on the actual system implementation. Execution of this instruction causes the TS68020 to run a breakpoint acknowledge bus cycle, with a 3-bit breakpoint identifier placed on address lines A2, A3, and A4. This 3-bit identifier permits up to eight breakpoints to be easily differentiated. The normal response to the TS68020 is an operation word (typically an instruction, originally replaced by the debugger with the breakpoint instruction) placed on the data lines by external debugger hardware and the breakpoint acknowledge cycle properly terminated. The TS68020 then executes this operation word in place of the breakpoint instruction. The debugger hardware can count the number of executions of each breakpoint and halt execution after a pre-determined number of cycles.

The TS68020 will always transfer the maximum amount of data on all bus cycles; i.e., it always assumes the port is 32-bit wide when beginning the bus cycle. In addition, the TS68020 has no restrictions concerning alignment of operands in memory; long word operands need not be aligned on long word address boundaries. When misaligned data requires multiple bus cycles, the TS68020 aligned data requires multiple bus cycles, the TS68020 automatically runs the minimum number of bus cycles.

The Co-processor Concept

The co-processor interface is a mechanism for extending the instruction set of the TS68000 Family. Examples of these extensions are the addition of specialized data operands for the existing data types or, for the case of the floating point, the inclusion of new data types and operations for them as implemented by the TS68881 and TS68882 floating point co-processors.

The programmer's model for the TS68000 Family of microprocessors is based on sequential, non-concurrent instruction execution. This means each instruction is completely executed prior to the beginning of the next instruction. Hence, instructions do not operate concurrently in the programmer's model. Most microprocessors implement the sequential model which greatly simplifies the programmer responsibilities since sequencing control is automatic and discrete.

The TS68000 co-processor interface is designed to extend the programmer's model and it provides full support for the sequential, non-concurrent instruction execution model. Hence, instruction execution by the co-processor is assumed to not overlap with instruction execution with the main microprocessor. Yet, the TS68000 co-processor interface does allow concurrent operation when concurrency can be properly accommodated. For example, the TS68881 or TS68882 floating-point co-processor will allow the TS68020 to proceed executing instruction while the co-processor continues a floating-point operation, up to the point that the TS68020 sends another request to the co-processor. Adhering to the sequential execution model, the request to the co-processor continues a floating-point operation, up to the co-processor completes each TS68881 and TS68882 instruction before it starts the next, and the TS68020 is allowed to proceed as it can in a concurrent fashion.

co-processors are divided into two types by their bus utilization characteristics. A co-processor is a DMA co-processor if it can control the bus independent of the main processor. A co-processor is a non-DMA co-processor if it does not have the capability of controlling the bus. Both co-processor types utilize the same protocol and main processor resources. Implementation of a co-processor as a DMA or non-DMA type is based primarily on bus bandwidth of the co-processor, performance, and cost issues.

The communication protocol between the main processor and the co-processor necessary to execute a co-processor instruction is based on a group of co-processor interface registers (Table 10) which are defined for the TS68000 Family co-processor interface. The TS68020 hardware uses standard TS68000 asynchronous bus cycles to access the registers. Thus, the co-processor doesn't require a special bus hardware; the bus interface implemented by a co-processor for its interface register set must only satisfy the TS68020 address, data, and control signal timing to guarantee proper communication with the main processor. The TS68020 implements the communication protocol with all co-processors in hardware (and microcode) and handles all operations automatically so the programmer is only concerned with the instructions and data types provided by the co-processor as extensions to the TS68020 instruction set and data types.

When the main processor encounters the next co-processor instruction, the main processor queries the co-processor until the co-processor is ready; meanwhile, the main processor can go on to service interrupts and do a context switch to execute other tasks, for example.

Each co-processor instruction type has specific requirements based on this simplified protocol. The co-processor interface may use as many extension words as requires to implement a co-processor instruction.

Primitives/Response

The response register is the means by which the co-processor communicates service requests to the main processor. The content of the co-processor response register is a primitive instruction to the main processor which is read during co-processor communication by the main processor. The main processor “executes” this primitive, thereby providing the services requires by the co-processor. Table 11 summarizes the co-processor primitives that the TS68020 accepts.

Exceptions

Kinds of Exceptions

Exception can be generated by either internal or external causes. The externally generated exceptions are the interrupts, the bus error, and reset requests. The interrupts are requests from peripheral devices for processor action while the bus error and reset pins are used for access control and processor restart. The internally generated exceptions come from instructions, address errors, tracing, or breakpoints. The TRAP, TRAPcc, TRAPV, cpTRAPcc, CHK, CHK2, and DIV instructions can all generate exceptions as part of their execution. Tracing behaves like a very high priority, internally generated interrupt whenever it is processed. The other internally generated exceptions are caused by illegal instructions, instruction fetches from odd addresses, and privilege violations.

Exception Processing Sequence

Exception processing occurs in four steps. During the first step, an internal copy is made of the status register. After the copy is made, the special processor state bits in the status register are changed. The S bit is set, putting the processor into supervisor privilege state. Also, the T1 and T0 bits are negated, allowing the exception handler to execute unhindered by tracing. For the reset and interrupt exceptions, the interrupt priority mask is also updated.

In the second step, the vector number of the exception is determined. For interrupts, the vector number is obtained by a processor read that is classified as an interrupt acknowledge cycle. For co-processor detected exceptions, the vector number is included in the co-processor exception primitive response. For all other exceptions, internal logic provides the vector number. This vector number is then used to generate the address of the exception vector.

The third step is to save the current processor status. The exception stack frame is created and filled on the supervisor stack. In order to minimize the amount of machine state that is saved, various stack frame sizes are used to contain the processor state depending on the type of exception and where it occurred during instruction execution. If the exception is an interrupt and the M bit is on, the M bit is forced off, and a short four word exception stack frame is saved on the master stack which indicates that the exception is saved on the interrupt stack. If the exception is a reset, the M bit is simply forced off, and the reset vector is accessed.

Package Mechanical Data

Figure 23. 114-lead - Ceramic Pin Grid Array

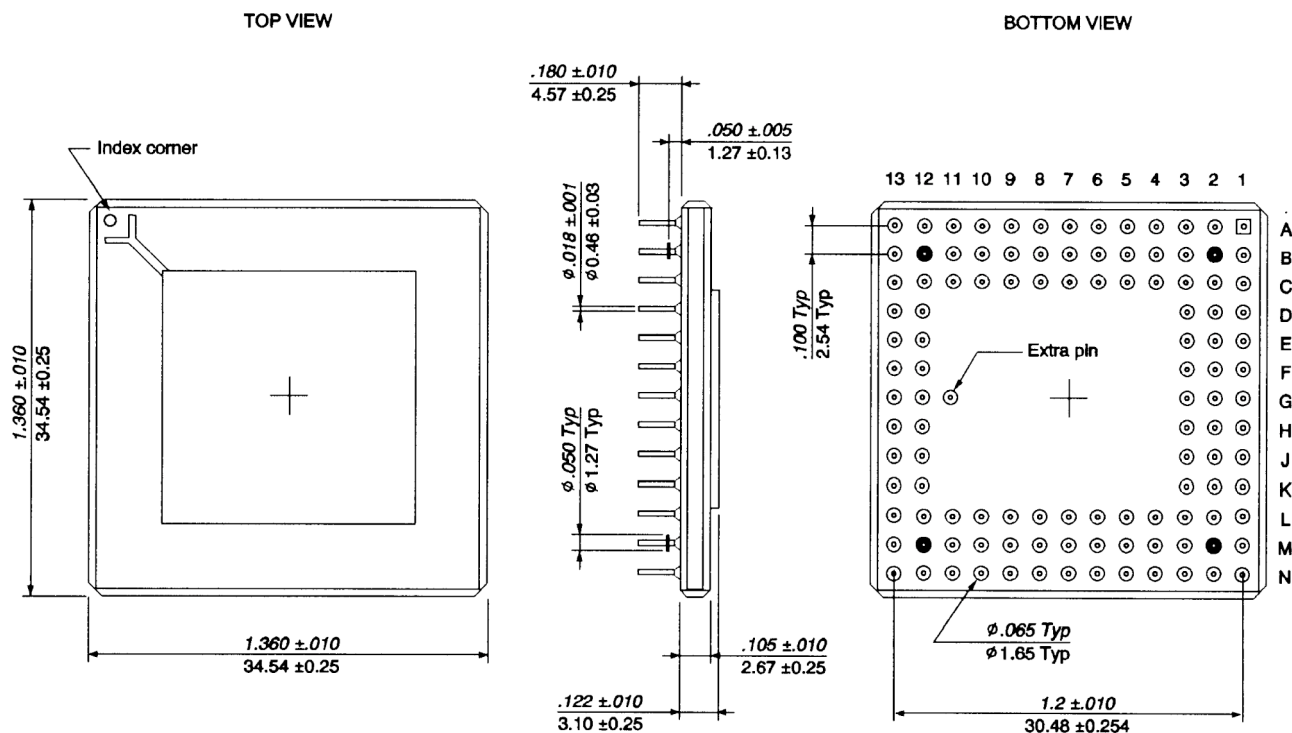


Figure 24. 132 Pins - Ceramic Quad Flat Pack

